

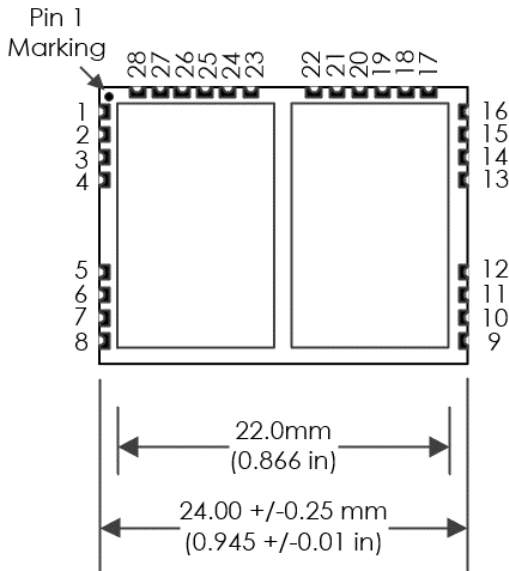
TFN150P1800x2400x400-28 Package Details

Metal 18.0mm x 24.0mm 28 Lead QFN

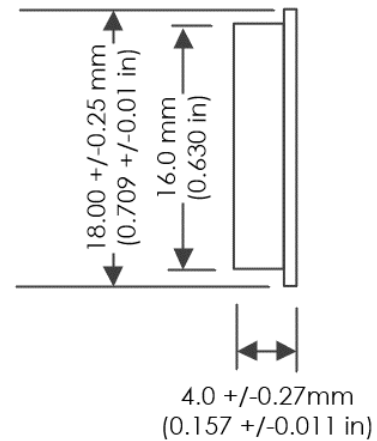


Package Drawing

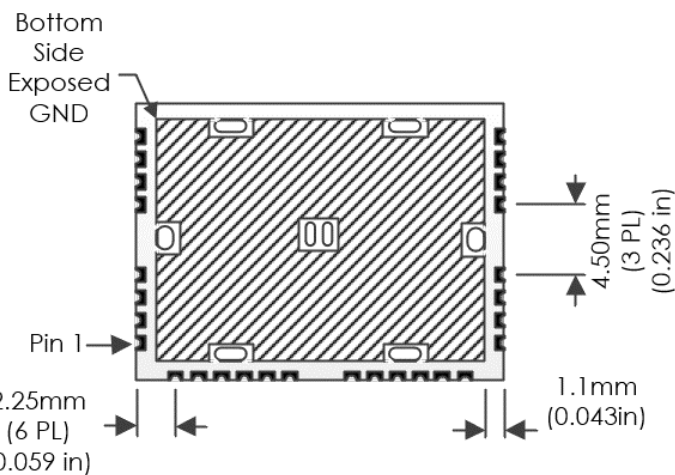
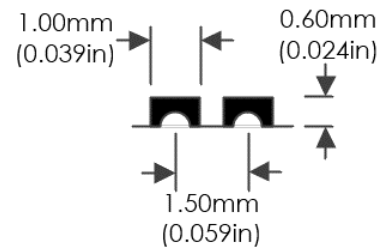
Top View



Side View



Pad and Spacing Detail



Bottom View

Notes:

1. All dimensions shown are in mm
2. Substrate material: Isola 370HR
3. Lid Material: Nickel Silver Alloy
4. Lead finish: ENEPIG
 - Ni: 3.00 um minimum
 - Pd: 0.05 um minimum
 - Au: 0.05 um minimum

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Recommended Assembly Procedure

It is recommended to attach the bottom side ground pad to the printed circuit board using a highly conductive silver epoxy and then hand solder the 28 pins along the part's perimeter to their intended printed circuit board pads using lead-free solder.

The recommended silver epoxy is MG Chemicals part 8331S and the recommended assembly thickness is 3 to 5 mils.

If the device is to be attached (both the ground pad and perimeter pins) to the circuit board using a typical lead-free solder reflow process reaching temperatures of 260C, the excessive temperature can cause internal parts to the filter bank to reflow and result in damage to the device. If a solder reflow process must be used, it is recommended to use a lower temperature leaded solder profile, typically 225C maximum.

Package Naming Convention

- TFN** – Three-Sided Flat No-Lead
- 150** – Pitch = 1.50mm
- 1800** – Body Width = 18.00mm
- 2400** – Body Length = 24.00mm
- 400** – Height = 4.00mm
- 28** – Pin Quantity

*Based on IPC-7351B naming convention

Revision History

Date	Revision Number	Notes
October 7, 2020	1	Initial Release
April 21, 2021	1.1	Package Drawing Dimensions Corrected
March 4, 2024	1.2	Corrected Lid Material to be Nickel Silver.